

[54] HEAT RELEASING PLATE FOR MOUNTING SEMICONDUCTOR COMPONENTS

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[**] Term: 14 Years

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[52] U.S. Cl. D13/23

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[56]

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[57]

CLAIM

The ornamental design for a heat releasing plate for mounting semiconductor components, as shown and described.

DESCRIPTION

FIG. 1 is a front view of the heat releasing plate for mounting semiconductor components showing the new design;

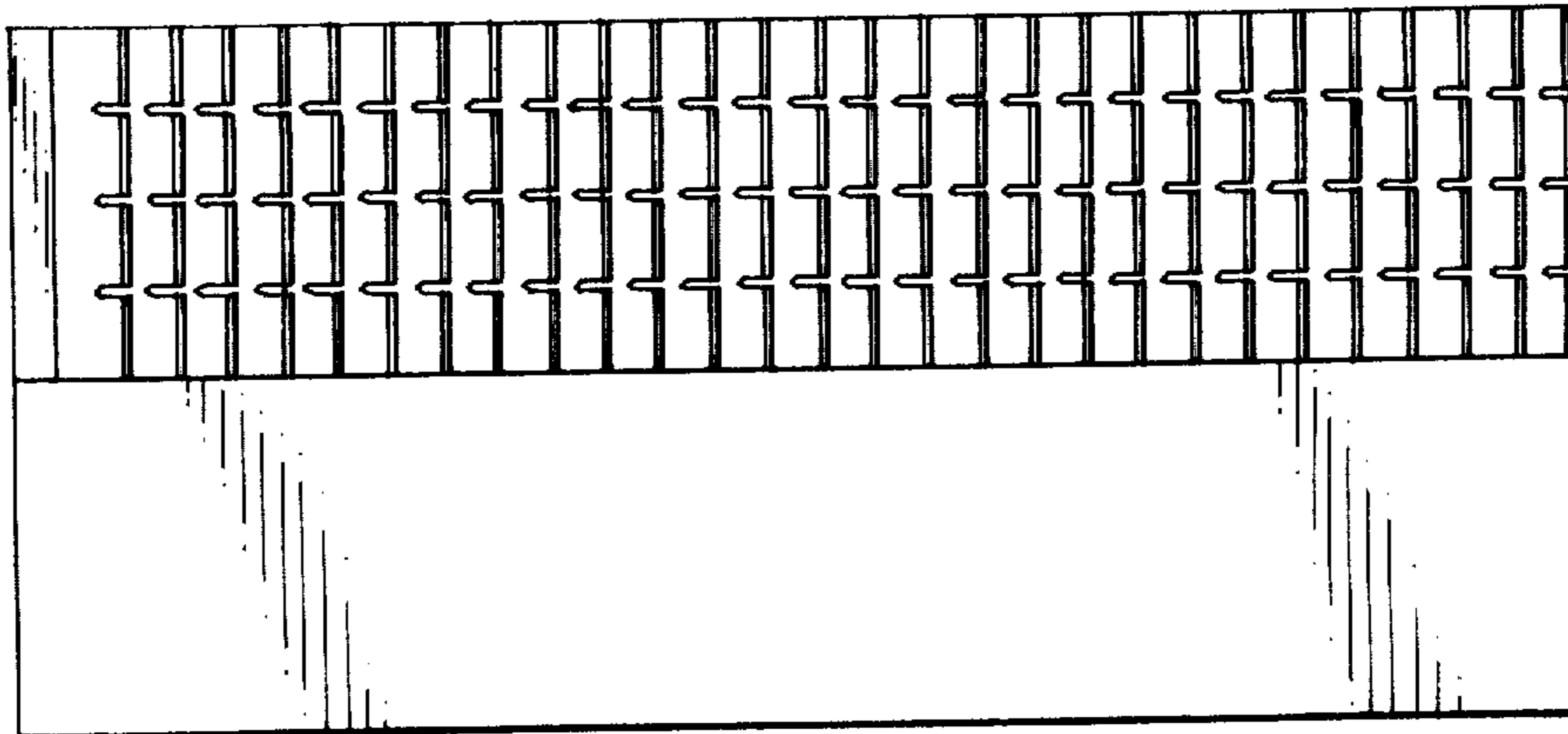
FIG. 2 is a plan view thereof;

FIG. 3 is a rear view thereof;

FIG. 4 is a bottom view thereof;

FIG. 5 is a right side view thereof; and

FIG. 6 is a sectional view taken on line 6—6 of FIG. 1.



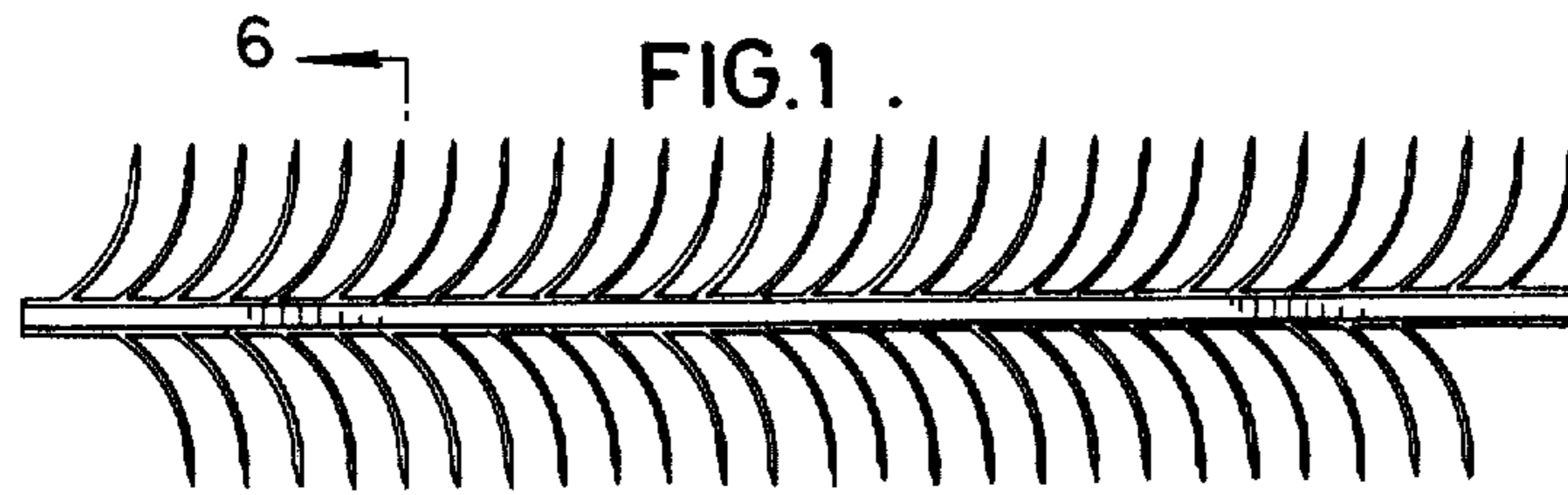


FIG. 1 .



FIG. 2 .

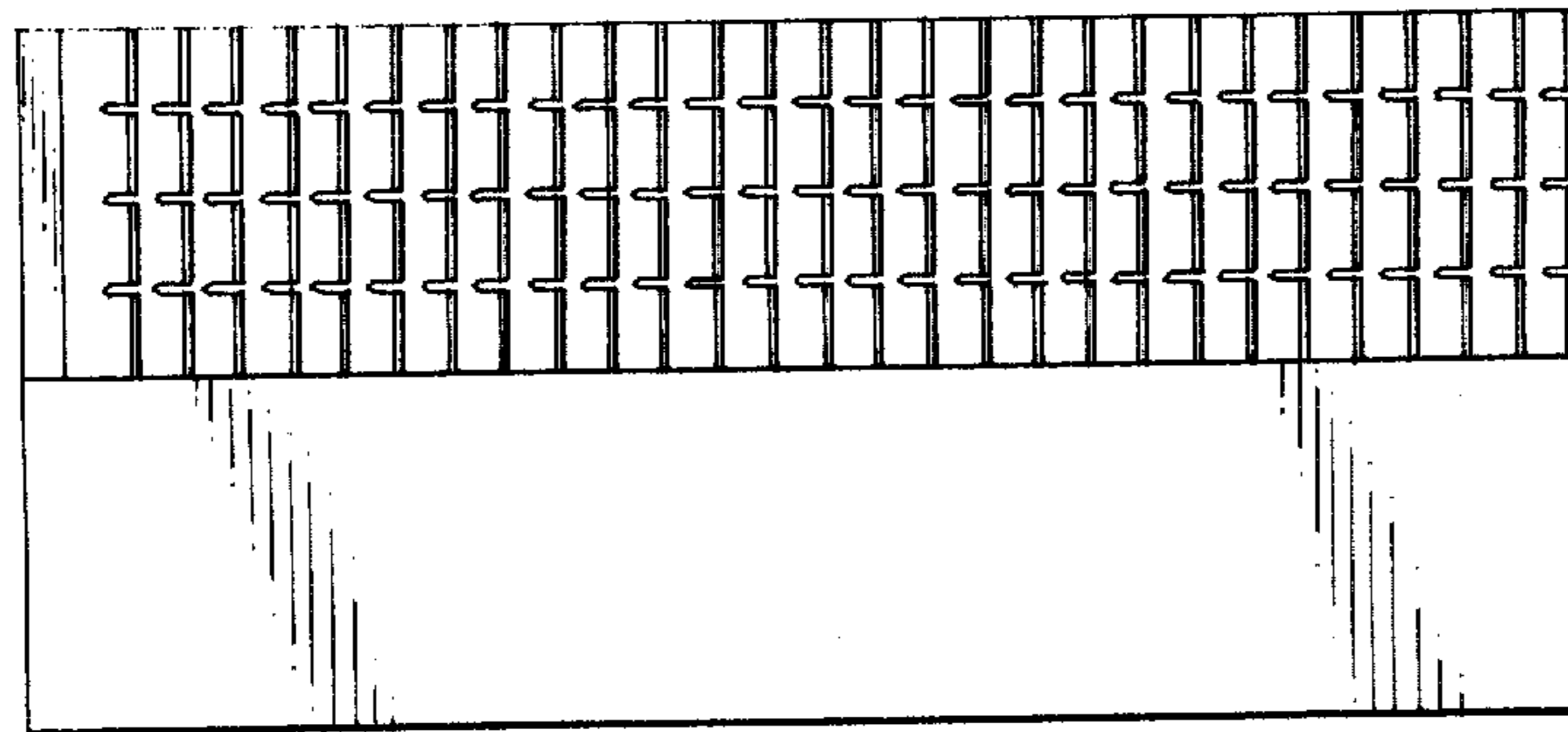


FIG. 3 .

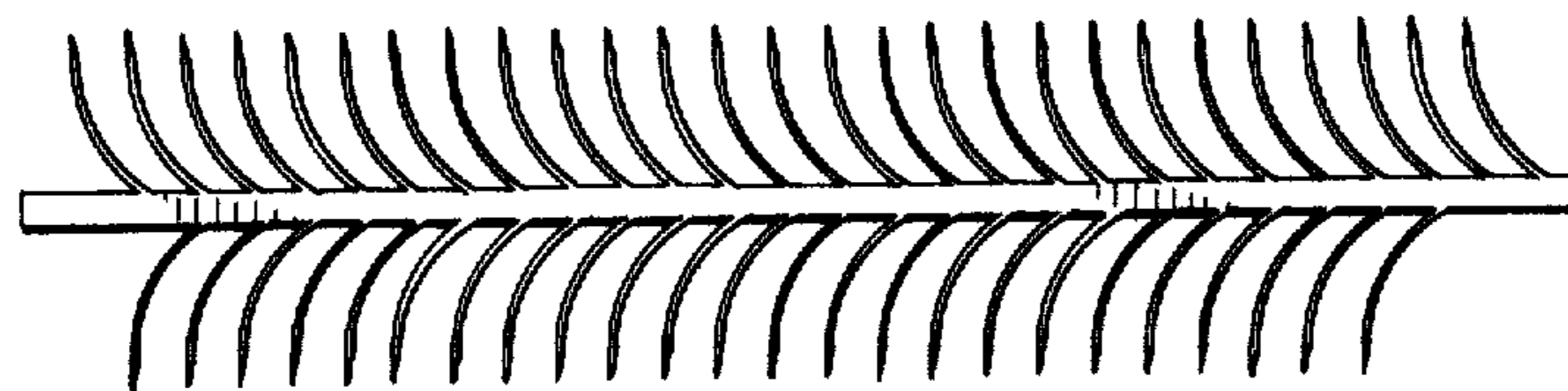


FIG. 4 .

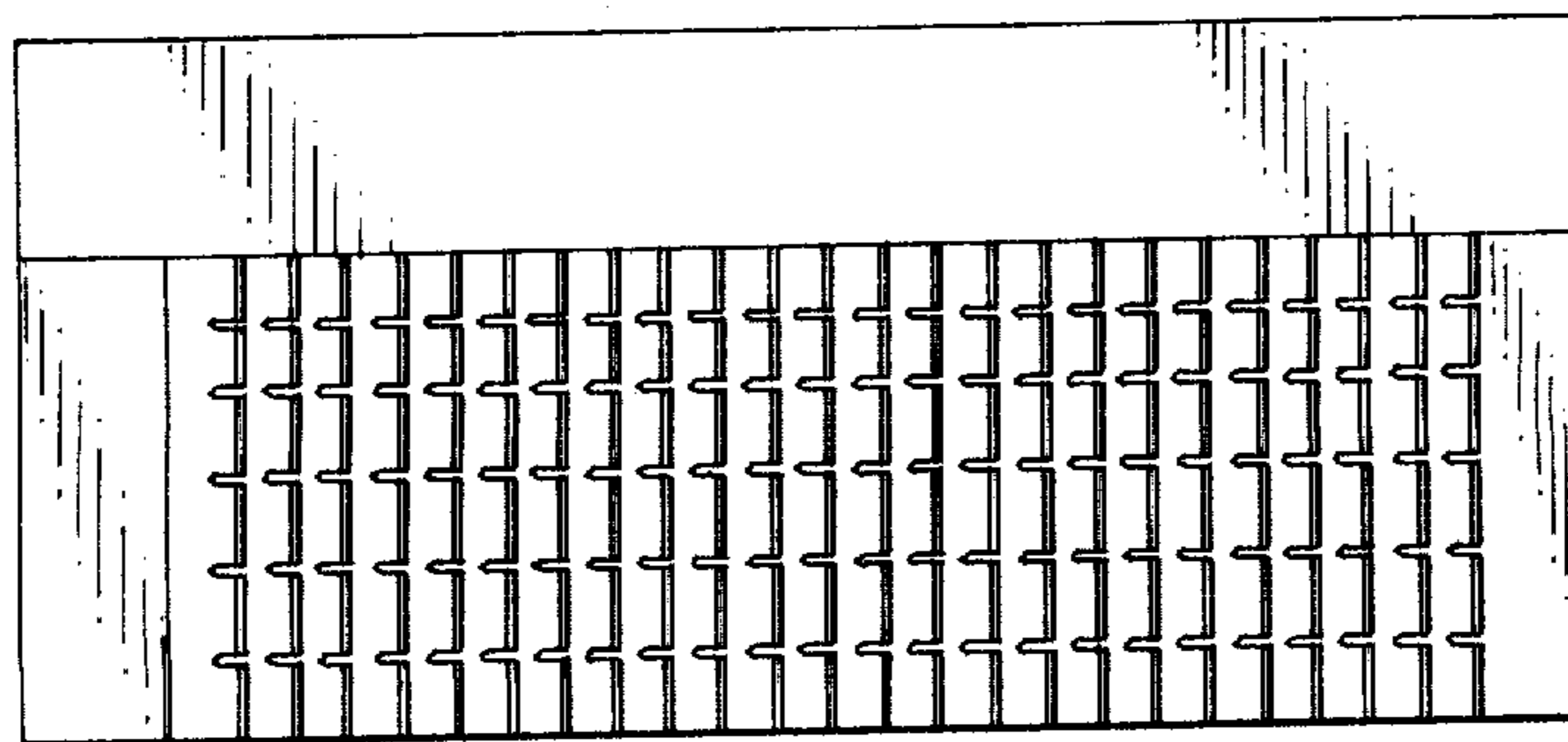


FIG. 5 .

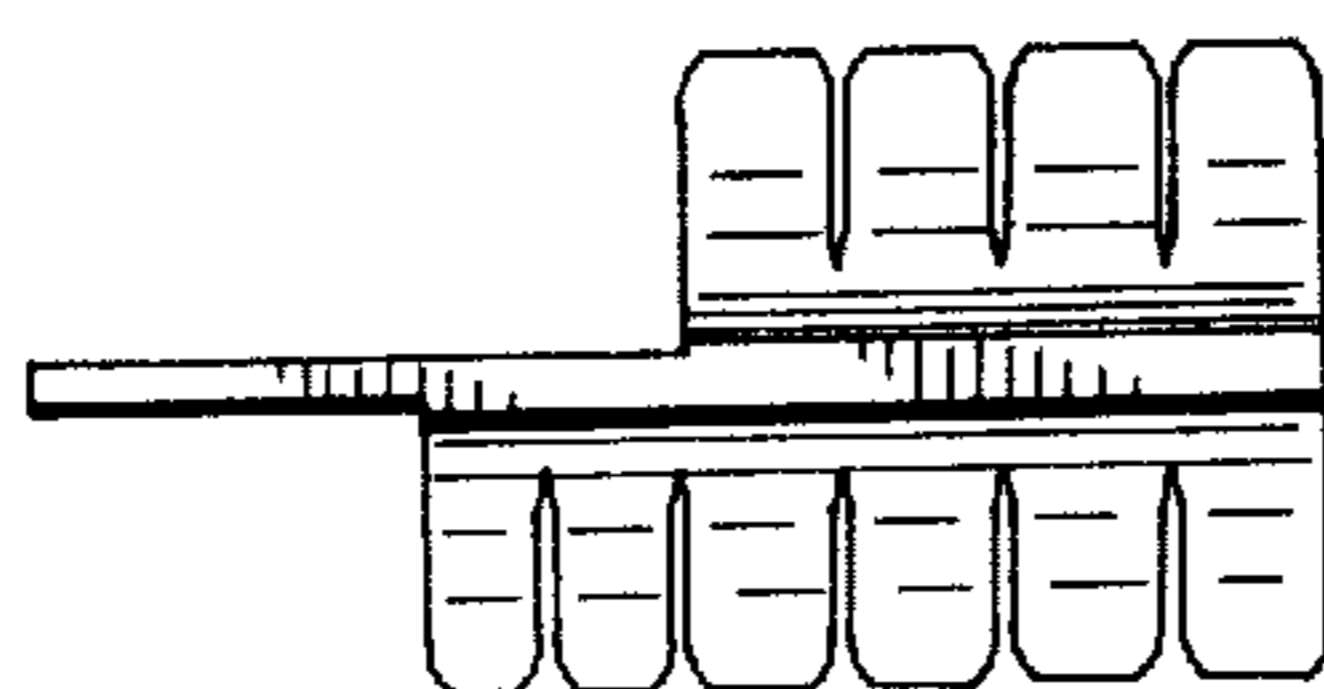


FIG. 6 .

